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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application of

Applicant : Kyozauro Takagi  
Serial No. : 10/005,195  
Filed : December 4, 2001  
Title : **RUSTICATION**  
Docket : : FUU 0008 PA

Assistant Commissioner for Patents  
Washington, DC 20231

Sir:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on March 4, 2002.

John B. Reed - Attorney

Reg. No. 46,506

INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR §§ 1.56, 1.97, AND 1.98

Applicant submits herewith patents, publications, and other information of which he is aware, which he believes may be material, as defined in 37 CFR §1.56(b), to the examination of this application and in respect of which there may be a duty to disclose in accordance with 37 CFR §1.56(a). While the information referred to in this Information Disclosure Statement may be material pursuant to 37 CFR §1.56(b), the filing of this Information Disclosure Statement is not intended to, pursuant to 37 CFR §1.97(h), constitute an admission that any patent, publication, or other information referred to is, or is considered to be, material to the patentability of this invention. Further, pursuant to 37 CFR §1.97(g), the filing of this Statement should not be construed as a statement that a search has been made or that no other material information exists.

A listing of all items of information cited is attached on PTO/SB/08A, a substitute for form 1449A/PTO. Copies of the items are enclosed for the convenience of the Examiner.

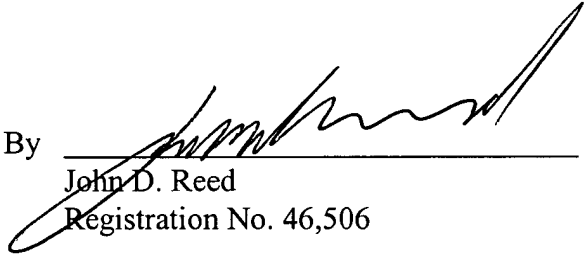
Pat. No. 10/005,195  
Docket No. FUU 0008 PA

This Information Disclosure Statement is being filed within the period set forth in 37 CFR §1.97(b) because it is filed within three months of the filing date of a national application or within three months of the date of entry of the national stage as set forth in 37 CFR §1.491 in an international application.

Respectfully submitted,

KILLWORTH, GOTTMAN, HAGAN  
& SCHAEFF, L.L.P.

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## INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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U.S. PATENT DOCUMENTS

## FOREIGN PATENT DOCUMENTS

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1 Applicant's unique citation designation number (optional). 2 See Kinds Codes of USPTO Patent Documents at [www.uspto.gov](http://www.uspto.gov) or MPEP 901.04. 3 Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). 4 For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. 5 Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. 6 Applicant is to place a check mark here if English language Translation is attached.

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